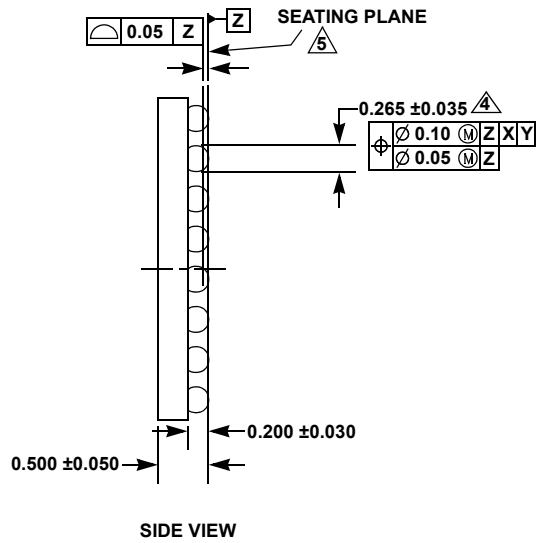
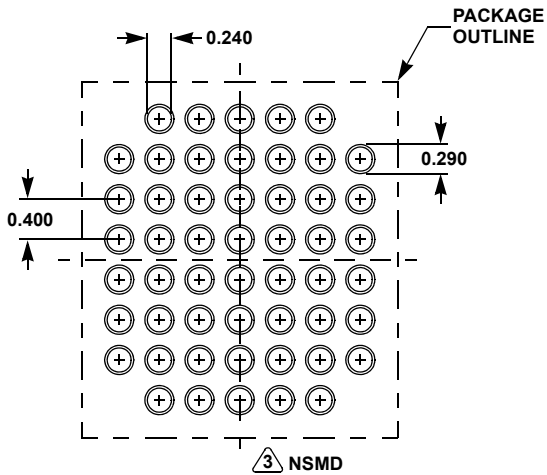
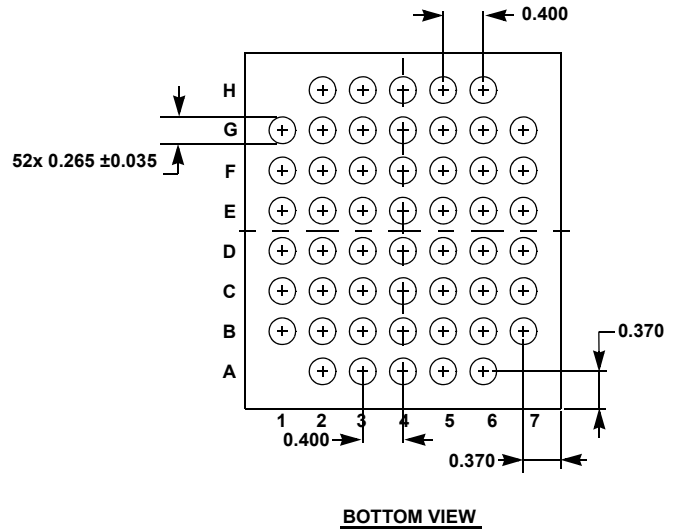
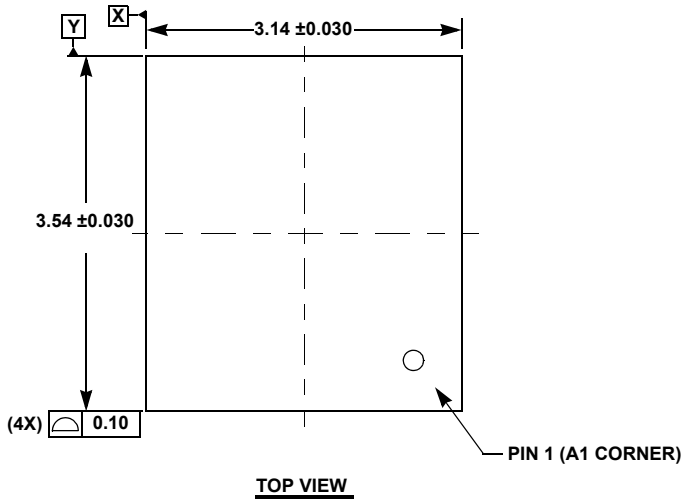


Package Outline Drawing

W7x8.52

7X8 ARRAY 52 BALLS WITH 0.40 PITCH WAFER LEVEL CHIP SCALE PACKAGE

Rev 1, 10/14



NOTES:

- All dimensions are in millimeters.
- Dimensions and tolerance per ASME Y 14.5M - 1994, and JESD 95-1 SPP-010.
- NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).
- Dimension is measured at the maximum bump diameter parallel to primary datum Z .
- Primary datum Z and seating plane are defined by the spherical crowns of the bump.